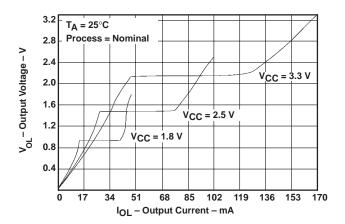
- **Member of the Texas Instruments** Widebus™ Family
- **EPIC™** (Enhanced-Performance Implanted **CMOS) Submicron Process**
- **DOC**[™] (Dynamic Output Control) Circuit **Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation**
- **Less Than 2-ns Maximum Propagation** Delay at 2.5-V and 3.3-V V_{CC}
- **Dynamic Drive Capability Is Equivalent to** Standard Outputs With IOH and IOL of ±24 mA at 2.5-V V_{CC}

- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- Ioff Supports Partial-Power-Down Mode Operation
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- **Package Options Include Plastic Thin** Shrink Small-Outline (DGG) and Thin Very Small-Outline (DGV) Packages

description

A Dynamic Output Control (DOC) circuit is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical V_{OI} vs I_{OI} and V_{OH} vs I_{OH} curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, AVC Logic Family Technology and Applications, literature number SCEA006, and Dynamic Output Control (DOC™) Circuitry Technology and Applications, literature number SCEA009.



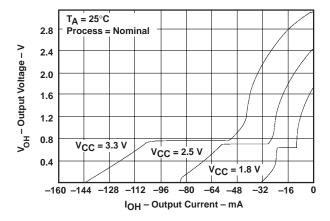


Figure 1. Output Voltage vs Output Current

This 16-bit buffer/driver is operational at 1.2-V to 3.6-V V_{CC} , but is designed specifically for 1.65-V to 3.6-V V_{CC} operation.

The SN74AVC16244 is designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The device can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. It provides true outputs and symmetrical active-low output-enable (\overline{OE}) inputs.



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description (continued)

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The SN74AVC16244 is characterized for operation from -40°C to 85°C.

terminal assignments

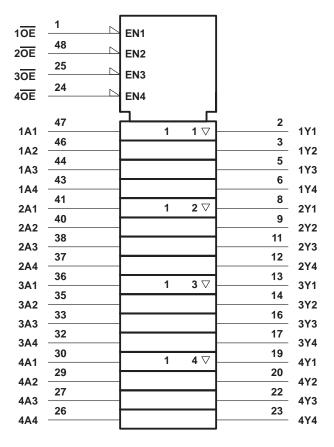
DGG OR DGV PACKAGE (TOP VIEW) 10E 48 ∏ 2OE 47 1 1A1 1Y1 🛮 2 1Y2 🛮 3 46 1A2 GND II4 45 GND 1Y3 **[**] 5 44 🛮 1A3 1Y4 **[**] 6 43 🛮 1A4 v_{cc} [7 42 V_{CC} 2Y1 41 2A1 8 2Y2 II 9 40 1 2A2 GND 10 39 GND 2Y3 [] 11 38 2A3 2Y4 [] 12 37 2A4 3Y1 13 36 3A1 3Y2 114 35 3A2 GND 115 34 GND 3Y3 116 33 🛮 3A3 3Y4 **1**17 32 3A4 V_{CC} 18 31 V_{CC} **[]** 19 4Y1 30 4A1 4Y2 **[**] 20 29 4A2 GND [21 28 ∏ GND 4Y3 **1**22 27 4A3 4Y4 🛮 23 26 **1** 4A4 4OE 24 25 3OE

FUNCTION TABLE (each 4-bit buffer)

INPU	JTS	OUTPUT
OE	Α	Υ
L	L	L
L	Н	Н
Н	Χ	Z

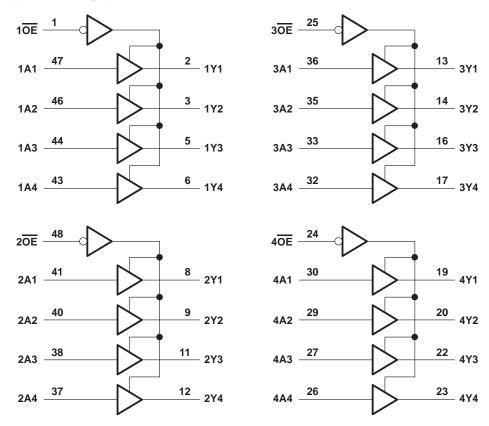


logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	–0.5 V to 4.6 V
Voltage range applied to any output in the high-impedance or power-off state, VO	
(see Note 1)	–0.5 V to 4.6 V
Voltage range applied to any output in the high or low state, VO	
(see Notes 1 and 2)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through each V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3): DGG package	70°C/W
DGV package	58°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.



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recommended operating conditions (see Note 4)

			MIN	MAX	UNIT		
V/00	Supply voltage	Operating	1.4	3.6	V		
VCC	Su pp iy voltage	Data retention only	1.2		V		
		V _{CC} = 1.2 V	VCC				
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$	0.65 × V _{CC}				
V_{IH}	High-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V _{CC}		V		
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7				
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	2				
		V _{CC} = 1.2 V		GND			
		V _{CC} = 1.4 V to 1.6 V		0.35 × V _{CC}			
V_{IL}	Low-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$	V		
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7			
		V _{CC} = 3 V to 3.6 V		0.8			
٧ _I	Input voltage		0	3.6	V		
\/-	Output voltage	Active state	0	VCC	V		
VO	Output voltage	3-state	0	3.6	V		
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		-2			
lavia	Static high-level output current [†]	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	V _{CC} = 1.65 V to 1.95 V				
IOHS		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-8	mA		
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		-12			
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$		2			
lols	Static low-level output current [†]	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		4	mA		
	Static low-level output current	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		8			
		$V_{CC} = 3 V \text{ to } 3.6 V$		12			
$\Delta t/\Delta v$	Input transition rise or fall rate	V _{CC} = 1.4 V to 3.6 V		5	ns/V		
TA	Operating free-air temperature		-40	85	°C		

[†] Dynamic drive capability is equivalent to standard outputs with I_{OH} and I_{OL} of ±24 mA at 2.5-V V_{CC}. See Figure 1 for V_{OL} vs I_{OL} and V_{OH} vs I_{OH} characteristics. Refer to the TI application reports, *AVC Logic Family Technology and Applications*, literature number **SCEA006**, and *Dynamic Output Control (DOC™) Circuitry Technology and Applications*, literature number **SCEA009**.

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST (TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT	
		I _{OHS} = -100 μA		1.4 V to 3.6 V	V _{CC} -0.	.2			
		$I_{OHS} = -2 \text{ mA},$	V _{IH} = 0.91 V	1.4 V	1.05				
Vон		$I_{OHS} = -4 \text{ mA},$	V _{IH} = 1.07 V	1.65 V	1.2			V	
		$I_{OHS} = -8 \text{ mA},$	V _{IH} = 1.7 V	2.3 V	1.75				
		$I_{OHS} = -12 \text{ mA},$	V _{IH} = 2 V	3 V	2.3				
		I _{OLS} = 100 μA		1.4 V to 3.6 V			0.2		
		$I_{OLS} = 2 \text{ mA},$	$V_{IL} = 0.49 \ V$	1.4 V			0.4		
VOL		$I_{OLS} = 4 \text{ mA},$	$V_{IL} = 0.57 V$	1.65 V			0.45	V	
		$I_{OLS} = 8 \text{ mA},$	$V_{IL} = 0.7 V$	2.3 V			0.55		
	-	$I_{OLS} = 12 \text{ mA},$	$V_{IL} = 0.8 V$	3 V			0.7		
IĮ	Control inputs	$V_I = V_{CC}$ or GND		3.6 V			±2.5	μΑ	
l _{off}		V_I or $V_O = 3.6 V$		0			±10	μΑ	
loz		$V_O = V_{CC}$ or GND		3.6 V			±10	μΑ	
Icc		$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			40	μΑ	
	Control inputs $V_I = V_{CC}$ or GND	Vi = Voc or GND		2.5 V		3.5			
Ci		AL = ACC OLGIAD		3.3 V	3.5	pF			
Ci	Data inputs $V_I = V_{CC}$ or GND		2.5 V		6		pi		
		AL = ACC OLGIAD	AI = ACC OL GIAD			6			
Co	Outputs	Vo = Voo or GND	Vo – Voo or CND			6.5		pF	
	Ουτραίο	Outputs $V_O = V_{CC}$ or GND		3.3 V		6.5			

[†] Typical values are measured at $T_A = 25$ °C.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 2 through 5)

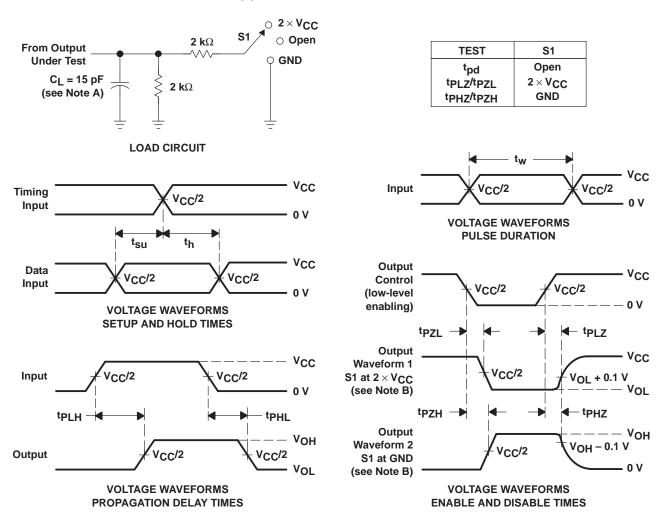
PARAMETER	FROM TO (INPUT) (OUTPUT)				V _{CC} = 1.5 V ± 0.1 V		V _{CC} = 1.8 V ± 0.15 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 3.3 V ± 0.3 V	
	(INFOT)	(001101)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
^t pd	А	Υ	3.1	0.6	3.3	0.7	2.9	0.6	1.9	0.5	1.7	ns
t _{en}	ŌĒ	Y	7.6	1.4	8	1.3	6.8	0.9	4	0.7	3.5	ns
^t dis	ŌĒ	Y	7.2	1.7	7.3	1.6	6.2	1	4.3	1	3.5	ns

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT		
		TEST CONDITIONS	TYP	TYP	TYP	ONIT		
Power dissipation		Outputs enabled	$C_1 = 0$, $f = 10 \text{ MHz}$	23	27	33	pF	
Cpd	capacitance	Outputs disabled	CL = 0, 1 = 10 MH2	0.1	0.1	0.1	pr	



PARAMETER MEASUREMENT INFORMATION V_{CC} = 1.2 V AND 1.5 V \pm 0.1 V

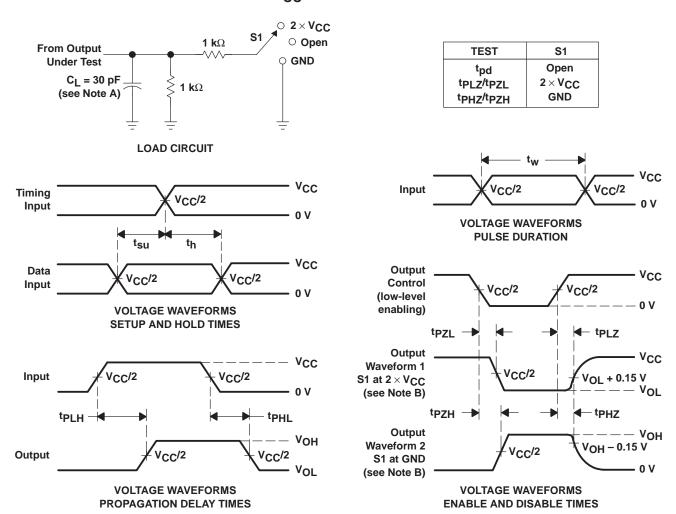


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2$ ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$

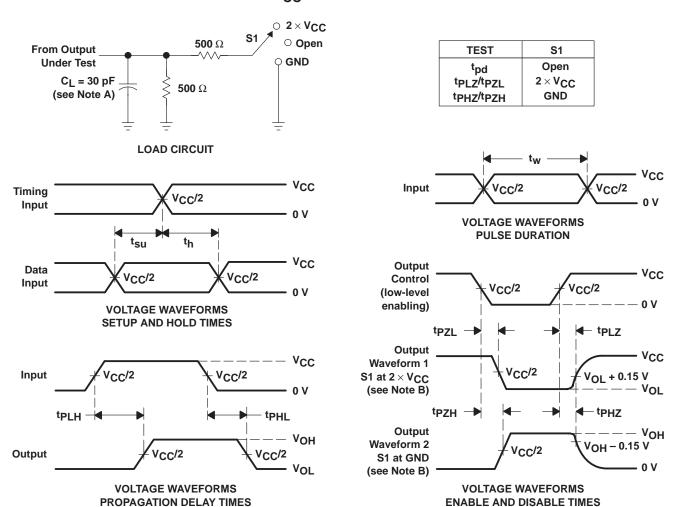


- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2$ ns, $t_f \leq 2$ ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms



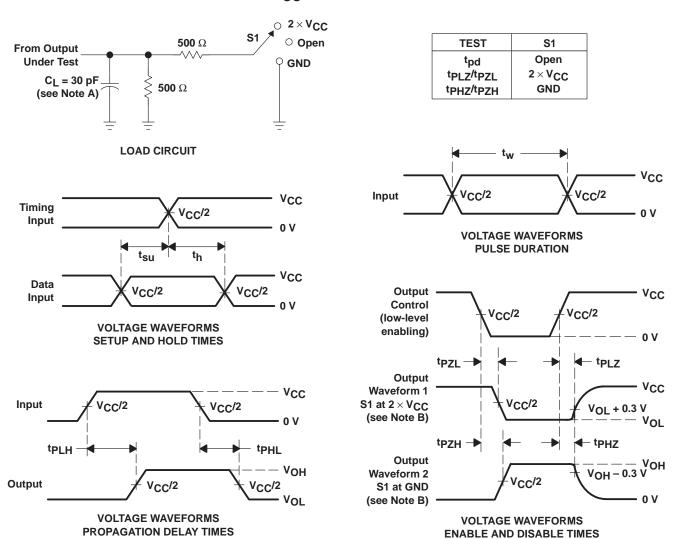
PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_f \leq 2 \ ns$, $t_f \leq 2 \ ns$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpl 7 and tpH7 are the same as tdis.
 - F. tpZL and tpZH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 4. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$



- NOTES: A. C_I includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \ \Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpl 7 and tpH7 are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tplH and tpHL are the same as tpd.

Figure 5. Load Circuit and Voltage Waveforms



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